

# HOSTAFORM® S 27072 WS 10/1570

## HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM-HI Molding compound ISO 29988- POM-K, M-GCLP, 05-001  
Modified POM copolymer Easy flowing, elastomer-containing injection molding type in black color with high carbon content; especially weathering resistant; lower chemical resistance than unmodified acetal copolymer; high resistance to thermal and oxidative degradation. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm. Ranges of applications: for molded parts with matt surface. FMVSS = Federal Motor Vehicle Safety Standard (USA)

### Product information

Resin Identification	POM-HI	ISO 1043
Part Marking Code	>POM-HI<	ISO 11469

### Rheological properties

Melt volume-flow rate	21 cm <sup>3</sup> /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage, parallel	1.8 <sup>[1]</sup> %	ISO 294-4, 2577
Moulding shrinkage, normal	1.9 <sup>[1]</sup> %	ISO 294-4, 2577
[1]: @ 195°C		

### Typical mechanical properties

Tensile modulus	2000 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	46 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8 %	ISO 527-1/-2
Nominal strain at break	35 %	ISO 527-1/-2
Flexural modulus	2100 MPa	ISO 178
Tensile creep modulus, 1h	1800 MPa	ISO 899-1
Tensile creep modulus, 1000h	1000 MPa	ISO 899-1
Charpy impact strength, 23°C	150 <sup>[P]</sup> kJ/m <sup>2</sup>	ISO 179/1eU
Charpy impact strength, -30°C	110 kJ/m <sup>2</sup>	ISO 179/1eU
Charpy notched impact strength, 23°C	11 kJ/m <sup>2</sup>	ISO 179/1eA
Charpy notched impact strength, -30°C	8 kJ/m <sup>2</sup>	ISO 179/1eA
Puncture energy, 23°C	10 J	ISO 6603-2
Ball indentation hardness, H 358/30	115 MPa	ISO 2039-1
Poisson's ratio	0.4 <sup>[C]</sup>	

[P]: Partial Break

[C]: Calculated

### Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	84 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120 E-6/K	ISO 11359-1/-2

### Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.7 %	Sim. to ISO 62
Density	1390 kg/m <sup>3</sup>	ISO 1183

# HOSTAFORM® S 27072 WS 10/1570

## HOSTAFORM®

### Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	200 °C
Min. melt temperature	190 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	65 °C
Min. mould temperature	60 °C
Max. mould temperature	70 °C
Hold pressure range	60 - 120 MPa
Back pressure	2 MPa

### Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	High impact or impact modified, Light stabilised or stable to light, U.V. stabilised or stable to weather, High Flow

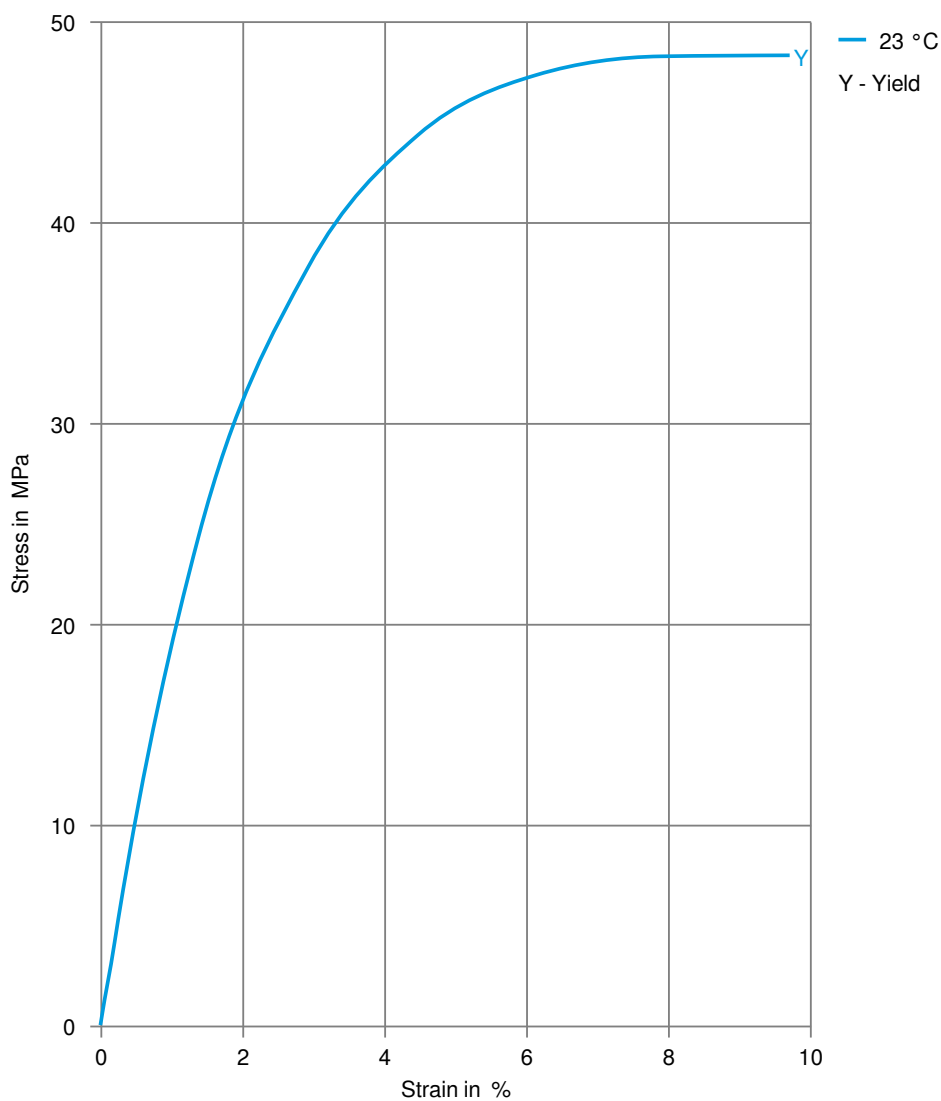
### Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Continental	TST N 055 54.17	
Li Auto	Q/LiA5310020	2021 (V2)

# HOSTAFORM® S 27072 WS 10/1570

## HOSTAFORM®

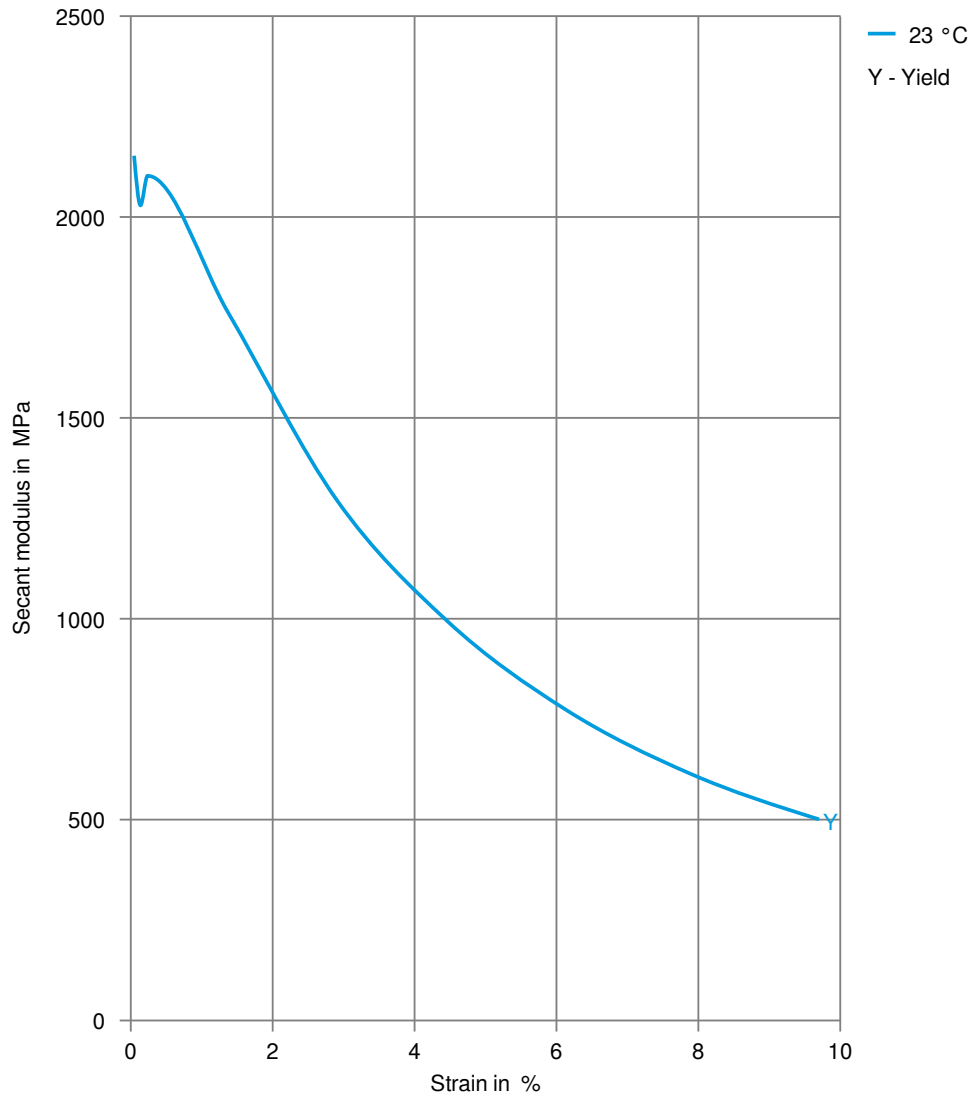
### Stress-strain



# HOSTAFORM® S 27072 WS 10/1570

HOSTAFORM®

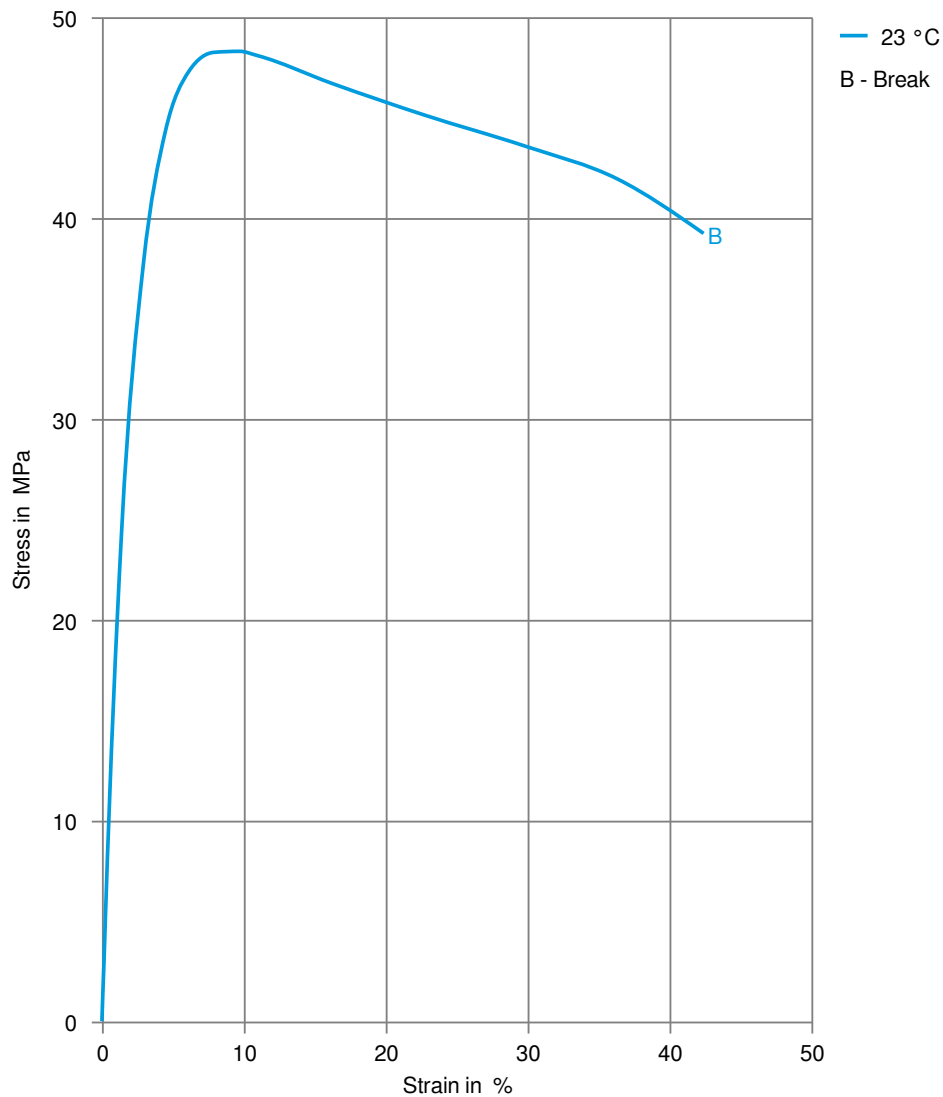
## Secant modulus-strain



# HOSTAFORM® S 27072 WS 10/1570

## HOSTAFORM®

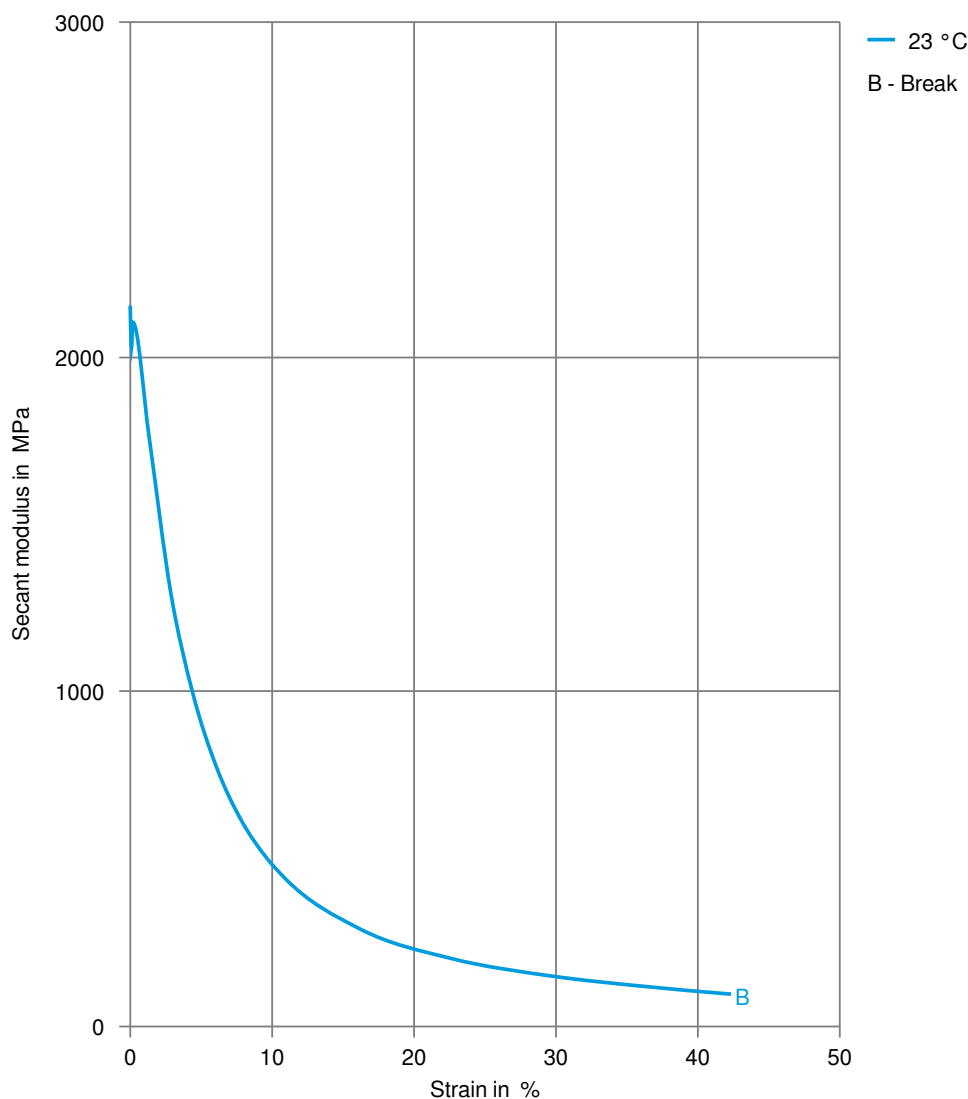
Stress-strain, 50mm/min



# HOSTAFORM® S 27072 WS 10/1570

## HOSTAFORM®

Secant modulus-strain, 50mm/min



Printed: 2025-05-30

Page: 6 of 6

Revised: 2024-12-03 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the manufacturer's current instructions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for additional technical information. Call Customer Services for the appropriate Materials Safety Data Sheets (MSDS) before attempting to process our products.

© 2025 Celanese or its affiliates. All rights reserved. Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates. Fortron is a registered trademark of Fortron Industries LLC.